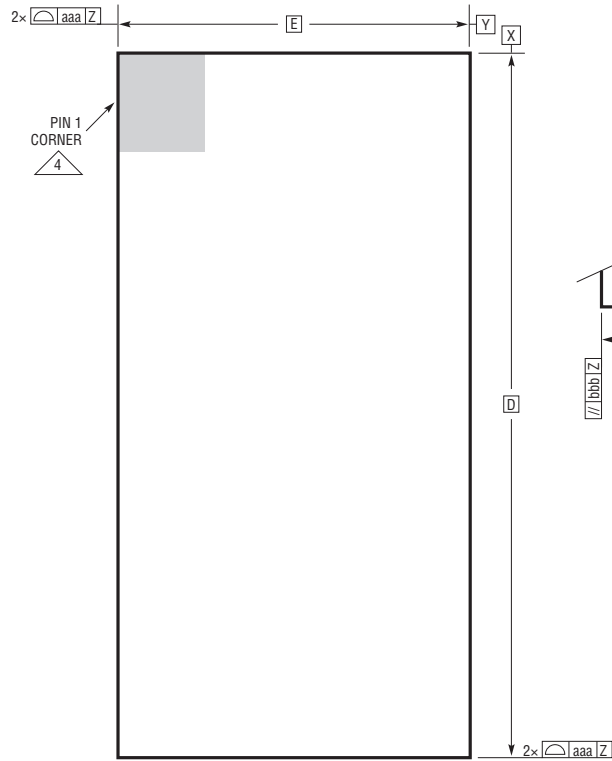
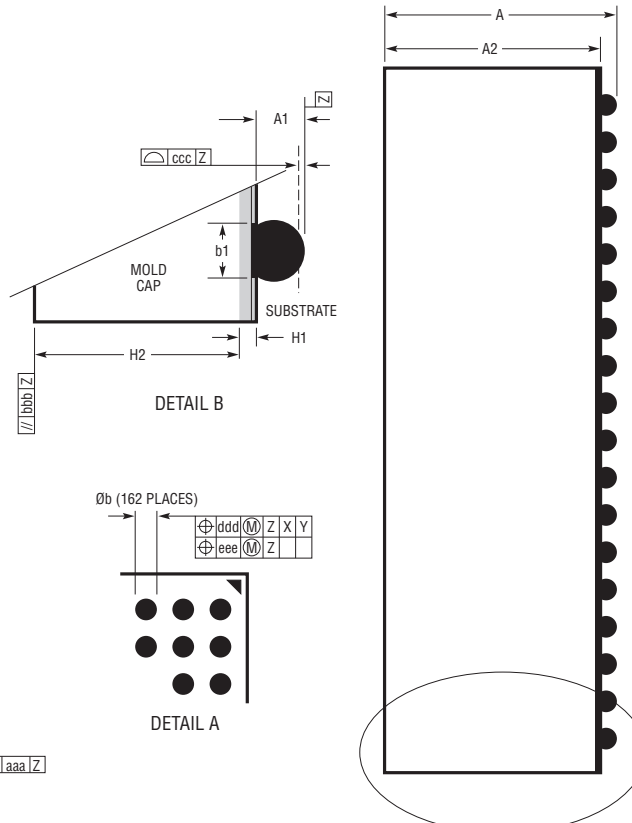


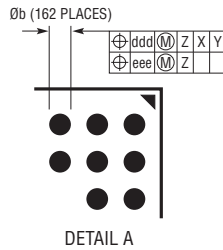
BGA Package
162-Lead (15mm × 7.50mm × 4.60mm)
(Reference LTC DWG# 05-08-1646 Rev 0)



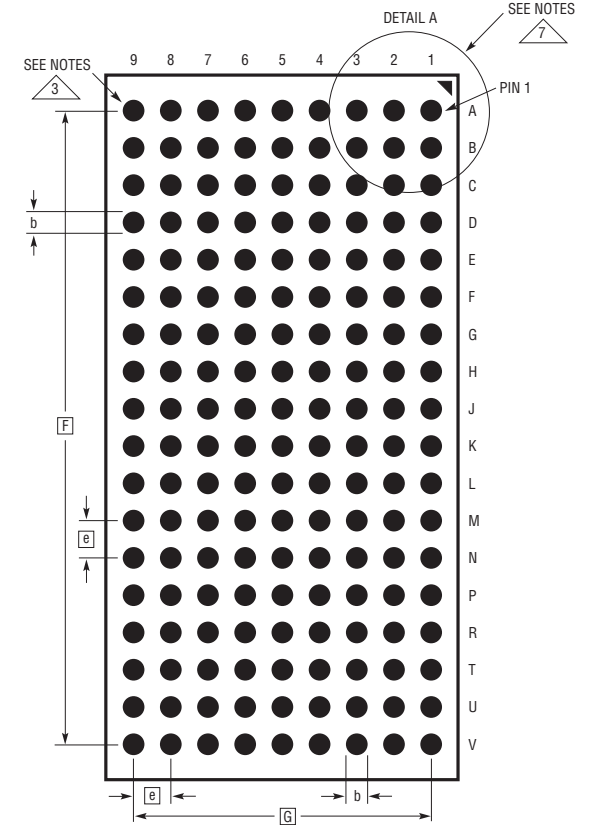
PACKAGE TOP VIEW



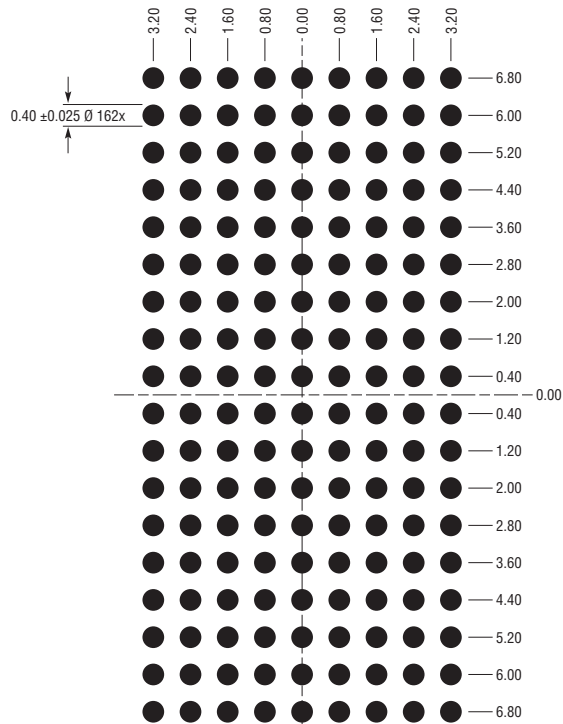
DETAIL B
PACKAGE SIDE VIEW



DETAIL A



PACKAGE BOTTOM VIEW

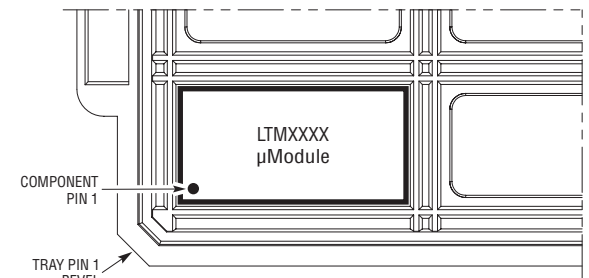


SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.41	4.60	4.79	
A1	0.30	0.40	0.50	BALL HT
A2	4.11	4.20	4.29	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		15.00		
E		7.50		
e		0.80		
F		13.60		
G		6.40		
H1		0.20 REF		SUBSTRATE THK
H2		4.00 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 162

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 - 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION